

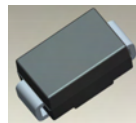
1.0A SURFACE MOUNT FAST RECOVERY RECTIFIER

Features

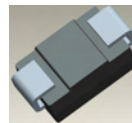
- Glass Passivated Die Construction
- Fast Recovery Time For High Efficiency
- Surge Overload Rating to 30A Peak
- Ideally Suited for Automated Assembly
- **Lead Free Finish/RoHS Compliant (Note 1)**
- **Green Molding Compound (No Halogen and Antimony) (Note 2)**

Mechanical Data

- Case: SMA/SMB
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 ⁽³⁾
- Polarity: Cathode Band or Cathode Notch
- Weight: SMA - 0.064 grams (approximate)
SMB - 0.093 grams (approximate)



Top View



Bottom View

PDF Support

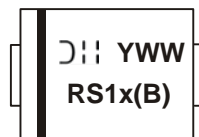
Ordering Information (Note 3)

Part Number	Case	Packaging
RS1x-13-F	SMA	5000/Tape & Reel
RS1xB-13-F	SMB	3000/Tape & Reel

* x = Device type, e.g. RS1D-13-F (SMA package); RS1JB-13-F (SMB package).

- Notes:
1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes.
 2. Product manufactured with Data Code 0924 (week 24, 2009) and newer are built with Green Molding Compound.
 3. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



RS1x = Product Type Marking Code, ex: RS1G (SMA package)
 RS1xB = Product Type Marking Code, ex: RS1GB (SMB package)
 DII = Manufacturer's Code Marking
 YWW = Date Code Marking
 Y = Last Digit of Year (ex: 6 for 2006)
 WW = Week code (01 to 53)

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	RS1 A/AB	RS1 B/BB	RS1 D/DB	RS1 G/GB	RS1 J/JB	RS1 K/KB	RS1 M/MB	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage (Note 4)	V_{RRM} V_{RWM} V_R	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectified Output Current @ $T_T = 120^\circ\text{C}$	I_O	1.0							A
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	30							A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal (Note 5)	$R_{\theta JT}$	20	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	$^\circ\text{C}$

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	RS1 A/AB	RS1 B/BB	RS1 D/DB	RS1 G/GB	RS1 J/JB	RS1 K/KB	RS1 M/MB	Unit
Forward Voltage Drop @ $I_F = 1.0\text{A}$	V_{FM}	1.3							V
Peak Reverse Current @ $T_A = 25^\circ\text{C}$ at Rated DC Blocking Voltage (Note 4) @ $T_A = 125^\circ\text{C}$	I_{RM}	5.0 200							μA
Reverse Recovery Time (Note 6)	t_{rr}	150			250	500			ns
Typical Total Capacitance (Note 7)	C_T	15							pF

- Notes:
4. Short duration pulse test used to minimize self-heating effect.
 5. Valid provided that terminals are kept at ambient temperature.
 6. Reverse recovery test conditions: $I_F = 0.5\text{A}$, $I_R = 1.0\text{A}$, $t_{rr} = 0.25\mu\text{s}$. See figure 5.
 7. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

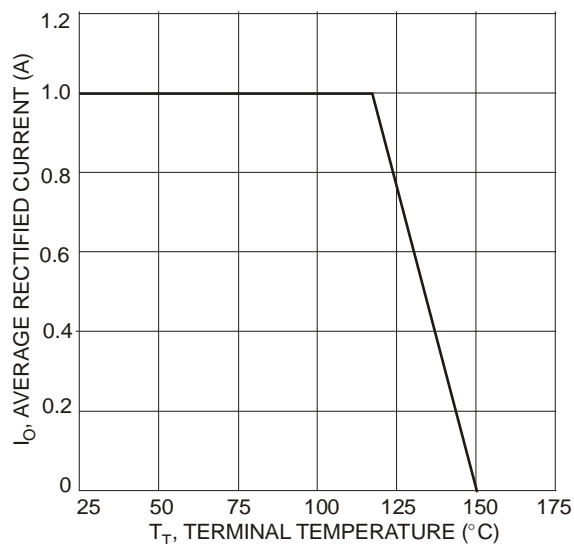


Fig. 1 Forward Current Derating Curve

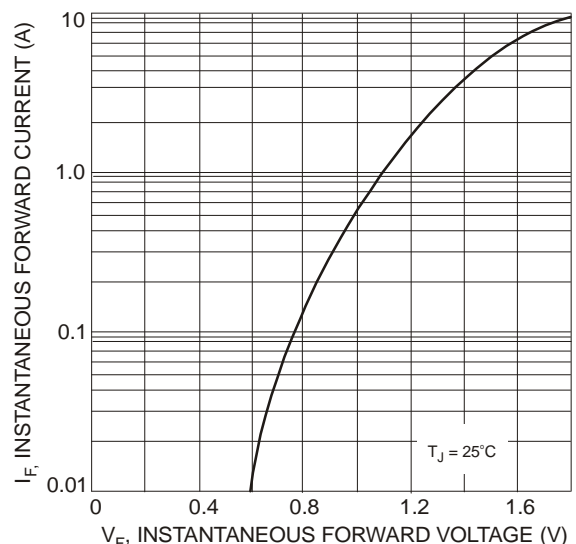


Fig. 2 Typical Forward Characteristics

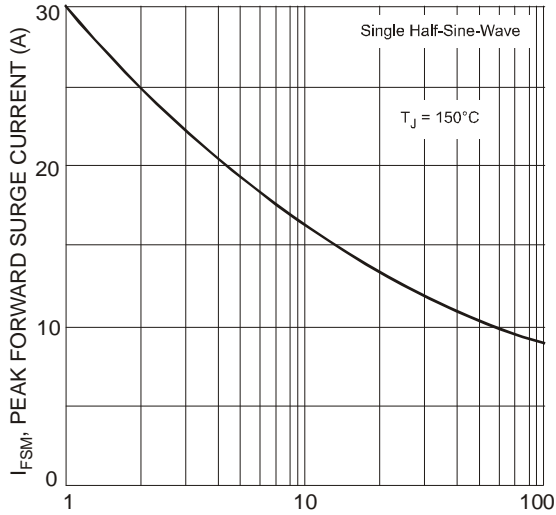


Fig. 3 Forward Surge Current Derating Curve

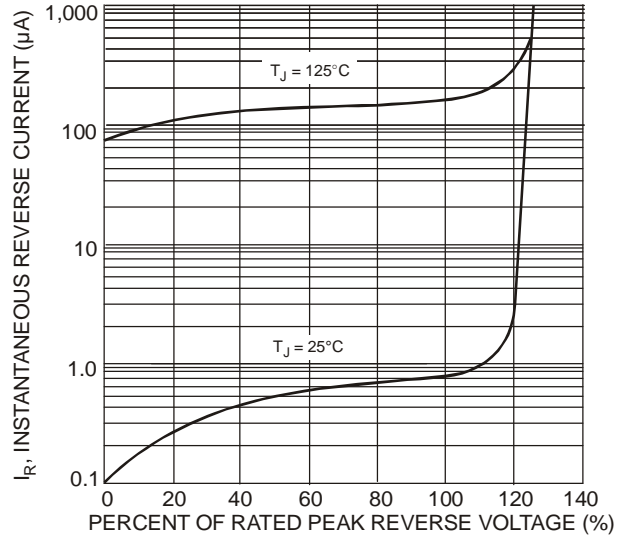
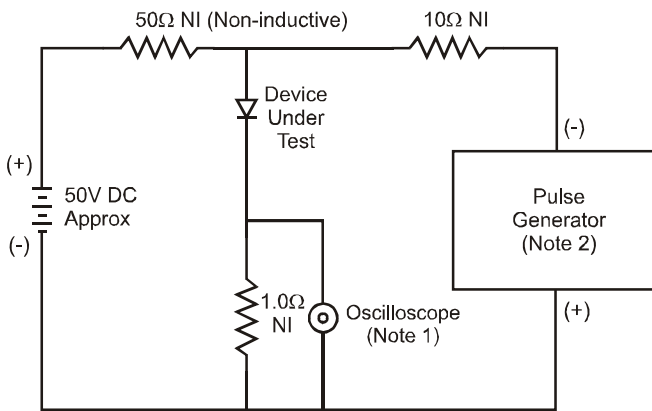
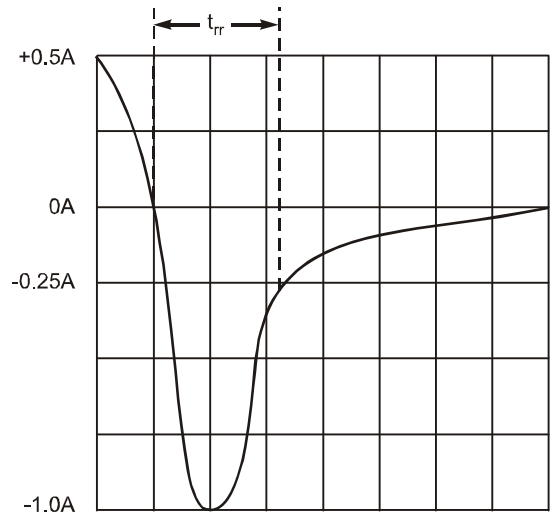


Fig. 4 Typical Reverse Characteristics



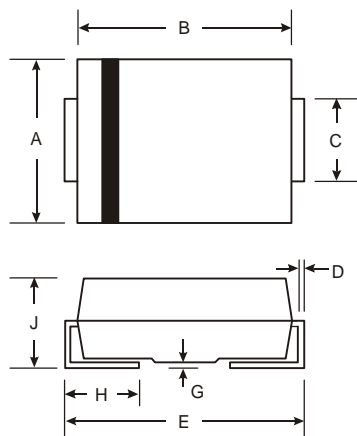
- Notes:
 1. Rise Time = 7.0ns max. Input Impedance = 1.0MΩ, 22pF.
 2. Rise Time = 10ns max. Input Impedance = 50Ω.



Set time base for 50/100 ns/cm

Fig. 5 Reverse Recovery Time Characteristic and Test Circuit

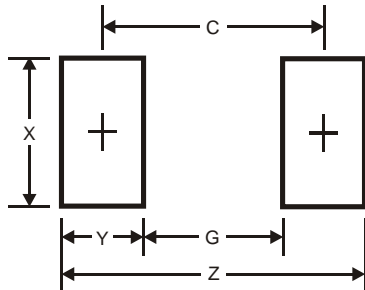
Package Outline Dimensions



SMA		
Dim	Min	Max
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.05	0.20
H	0.76	1.52
J	2.01	2.30
All Dimensions in mm		

SMB		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.57
C	1.96	2.21
D	0.15	0.31
E	5.00	5.59
G	0.05	0.20
H	0.76	1.52
J	2.00	2.50
All Dimensions in mm		

Suggested Pad Layout



SMA Dimensions	Value (in mm)
Z	6.5
G	1.5
X	1.7
Y	2.5
C	4.0

SMB Dimensions	Value (in mm)
Z	6.7
G	1.8
X	2.3
Y	2.5
C	4.3

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